Vishay Semiconductors



Molding Type Module IGBT, 2-in-1 Package, 1200 V and 400 A



Double INT-A-PAK

PRODUCT SUMMARY					
V _{CES}	1200 V				
I _C at T _C = 80 °C	400 A				
V _{CE(on)} (typical) at I _C = 400 A, 25 °C	1.70 V				
Speed	8 kHz to 30 kHz				
Package	Double INT-A-PAK				
Circuit	Half bridge				

FEATURES

- Low V_{CE(on)} trench IGBT technology
- Low switching losses
- 10 µs short circuit capability
- V_{CE(on)} with positive temperature coefficient
- Maximum junction temperature 150 °C
- · Low inductance case
- Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

- UPS
- Inverter for motor drive
- AC and DC servo drive amplifier

DESCRIPTION

Vishay's IGBT power module provides ultralow conduction loss as well as short circuit ruggedness. It is designed for applications such as general inverters and UPS.

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V _{CES}		1200	V
Gate to emitter voltage	V _{GES}		± 20	v
Collector current		T _C = 25 °C	600	
Collector current I _C	IC	T _C = 80 °C	400	
Pulsed collector current	I _{CM} ⁽¹⁾	t _p = 1 ms	800	А
Diode continuous forward current	١ _F	T _C = 80 °C	400	
Diode maximum forward current	I _{FM}	t _p = 1 ms	800	
Maximum power dissipation	PD	T _J = 150 °C	2119	W
Short circuit withstand time	t _{SC}	T _J = 125 °C	10	μs
RMS isolation voltage	V _{ISOL}	f = 50 Hz, t = 1 min	2500	V

Note

⁽¹⁾ Repetitive rating: pulse width limited by maximum junction temperature.

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IGBT ELECTRICAL SPECIFICATIONS ($T_C = 25$ °C unless otherwise noted)						
PARAMETER	SYMBOL TEST CONDITIONS MIN. TYP.		MAX.	UNITS		
Collector to emitter breakdown voltage	V _{(BR)CES}	$T_J = 25 \ ^{\circ}C$	1200	-	-	
Collector to emitter voltage	V _{CE(on)}	V_{GE} = 15 V, I _C = 400 A, T _J = 25 °C	-	1.70	2.15	v
Conector to ennitier voltage		V_{GE} = 15 V, I _C = 400 A, T _J = 125 °C	-	2.0	-	v
Gate to emitter threshold voltage	V _{GE(th)}	V_{CE} = V_{GE} , I_C = 16 mA, T_J = 25 °C	5.0	5.8	6.5	
Collector cut-off current	I _{CES}	$V_{CE} = V_{CES}, V_{GE} = 0 \text{ V}, \text{T}_{\text{J}} = 25 ^{\circ}\text{C}$	-	-	5.0	mA
Gate to emitter leakage current	I _{GES}	$V_{GE}=V_{GES},V_{CE}=0~V,T_{J}=25~^{\circ}C$	-	-	400	nA

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	t _{d(on)}		-	250	-	
Rise time	t _r		-	39	-	ns mJ
Turn-off delay time	t _{d(off)}	$V_{CC} = 600 \text{ V}, \text{ I}_{C} = 400 \text{ A}, \text{ R}_{g} = 1.8 \Omega,$	-	500	-	
Fall time	t _f	V _{GE} = ± 15 V, T _J = 25 °C	-	100	-	
Turn-on switching loss	E _{on}	7	-	17.0	-	
Turn-off switching loss	E _{off}	7	-	42.0	-	
Turn-on delay time	t _{d(on)}		-	299	-	ns
Rise time	tr	7	-	46	-	
Turn-off delay time	t _{d(off)}	$\begin{split} V_{CC} &= 600 \ V, \ I_C = 400 \ A, \ R_g = 1.8 \ \Omega, \\ V_{GE} &= \pm \ 15 \ V, \ T_J = 125 \ ^\circ C \end{split}$	-	605	-	
Fall time	t _f		-	155	-	
Turn-on switching loss	E _{on}	7	-	25.1	-	
Turn-off switching loss	E _{off}	7	-	61.9	-	- mJ
Input capacitance	C _{ies}		-	28.8	-	
Output capacitance	C _{oes}	V _{GE} = 0 V, V _{CE} = 25 V, f = 1.0 MHz	-	1.51	-	nF
Reverse transfer capacitance	C _{res}	7	-	1.31	-	
SC data	I _{SC}	$ \begin{split} t_{sc} &\leq 10 \; \mu s, V_{GE} = 15 \; V, T_J = 125 \; ^{\circ}C, \\ V_{CC} &= 600 \; V, V_{CEM} \leq 1200 \; V \end{split} $	-	1600	-	А
Internal gate resistance	R _{gint}		-	1.9	-	Ω
Stray inductance	L _{CE}		-	-	20	nH
Module lead resistance, terminal to chip	R _{CC'+EE'}	T _C = 25 °C	-	0.35	-	mΩ

DIODE ELECTRICAL SPECIFICATIONS ($T_c = 25$ °C unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS MIN. TYP.		MAX.	UNITS		
Diode forward voltage	V _F	V _F I _F = 400 A -	T _J = 25 °C	-	1.65	2.15	V
Didde forward voltage			T _J = 125 °C	-	1.65	-	
Diode reverse recovery charge	Q _{rr}		T _J = 25 °C	-	44	-	
Diode reverse recovery charge			T _J = 125 °C	-	78	-	μC
Diede zoels reverse recevers every	I _{rr}	$I_{F} = 400 \text{ A}, V_{B} = 600 \text{ V},$ $dI/dt = -6000 \text{ A}/\mu \text{s},$ $V_{GF} = -15 \text{ V}$	T _J = 25 °C	-	490	-	А
Diode peak reverse recovery current			T _J = 125 °C	-	555	-	A
Diada ana ang ang ang ang ang ang ang ang an	E		T _J = 25 °C	-	19.0	-	ml
Diode reverse recovery energy	E _{rec}	⊏rec	T _J = 125 °C	-	35.1	-	mJ

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THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Operating junction temperature range	TJ		-	-	150	°C
Storage temperature range	T _{STG}		-40	-	125	
Junction to case			-	-	0.059	
Diode	R _{thJC}		-	-	0.106	K/W
Case to sink	R _{thCS}	Conductive grease applied	-	0.035	-	
Mounting torque		Power terminal screw: M6	2.5 to 5.0		כ	Nm
Mounting torque		Mounting screw: M6	3.0 to 5.0			
Weight				300		g

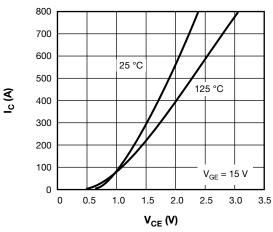


Fig. 1 - IGBT Typical Output Characteristics

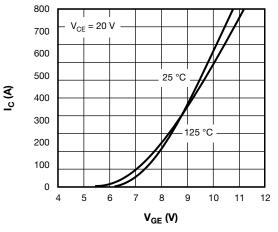
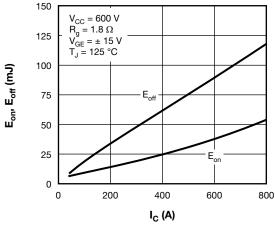
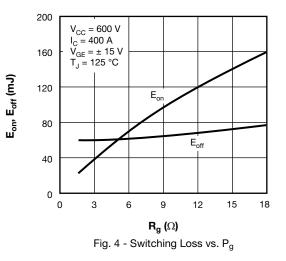


Fig. 2 - IGBT Typical Transfer Characteristics





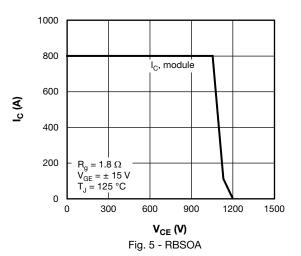


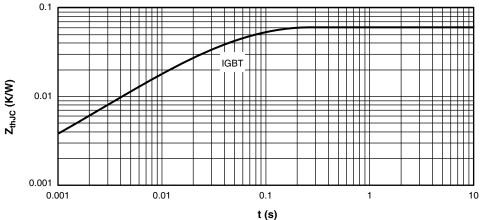
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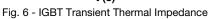
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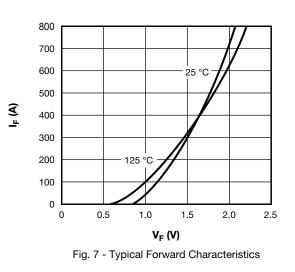


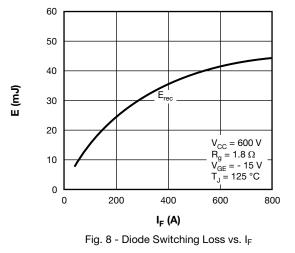
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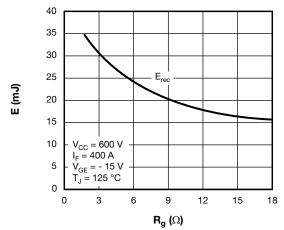
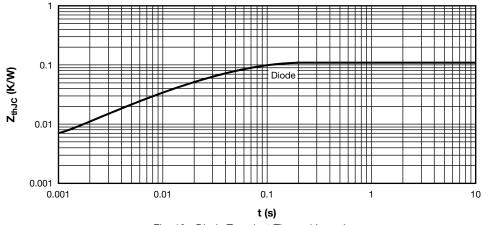
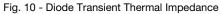


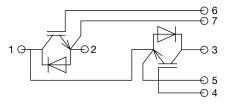
Fig. 9 - Diode Switching Loss vs. Gate Resistance





CIRCUIT CONFIGURATION

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LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95538			



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